

Sip Switches, Low Profile, Vertical and Right Angle

FEATURES:

- End-to-end stackable in .100" centre (SSV/SLV) versions
- High pressure wiping contacts allows aqueous or solvent cleaning
- Gas tight contacts (280,000 PSI)
- Ceramic substrate allows wave soldering temperature of 245° for up to 10 seconds (SLV Version)
- 2 SIP switches take up less board space than 1 DIP switch

ENVIRONMENTAL SPECIFICATIONS:

Operating Temperature.....-30°C to +85°C
 Storage Temperature-45°C to +100°C
 Solder Heat ResistanceWave soldering temperatures of 245°C ± 5°C with switch in off position 30 seconds when mounting on a .060" thick PCB per MIL-STD 202, Method 210

MATERIAL SPECIFICATIONS:

BasePPS 94V-0/Encapsulated Ceramic (SLV/SLH)
 CoverPBT 94V-0
 ContactsGold flashed Beryllium copper
 Actuator Material.....Polyamide
 Terminals/Fixed ContactsSolder coated copper alloy
 Terminal SealInsert moulded
 Process Seal.....Gas tight contacts

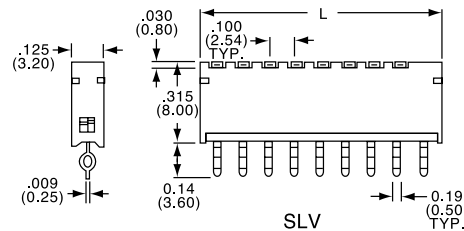
TYPICAL PERFORMANCE CHARACTERISTICS:

Contact Rating0.4 VA @ 20 VDC max.
 Initial Contact Resistance50 Milliohms max.
 Insulation Resistance100 Megohms min. @ 100 VDC
 Dielectric Strength.....500 VAC
 Actuation Force.....800 Grams max.
 Actuator Travel50°
 Life Expectancy.....1,000 Cycles

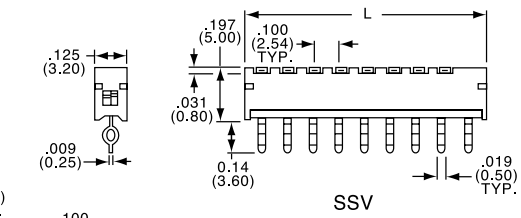
SSV



SSV08

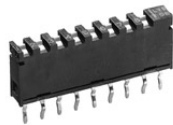


SLV



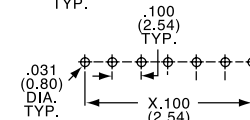
SSV

SLV



SLV08

Model	# Of Positions	"L" Dimension
SSV02	2	.298
SSV04	4	.498
SSV06	6	.698
SSV08	8	.898
SSV10	10	1.098
SLV04	4	.498
SLV08	8	.898



(n) INDICATES NUMBER OF POSITIONS

SLV and SSV

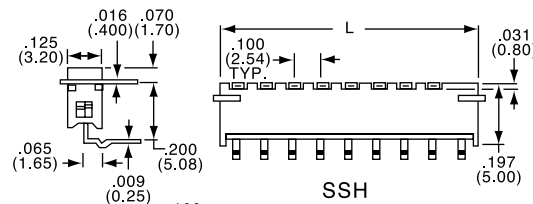


CIRCUIT DIAGRAM

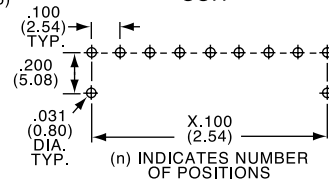
SSH



SSH06

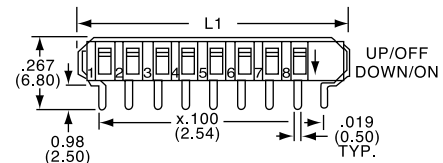


SSH



(n) INDICATES NUMBER OF POSITIONS

SSH

UP/OFF
DOWN/ON

CIRCUIT DIAGRAM

Model	# Of Positions	"L" Dimension	"L1" Dimension
SSH02	2	.298	.338
SSH04	4	.498	.538
SSH06	6	.699	.738
SSH08	8	.898	.938
SSH10	10	1.098	1.138